

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	64	("5523622").URPN.	USPAT	OR	ON	2006/04/19 10:33
L4	88	("5640048").URPN.	USPAT	OR	ON	2006/04/19 10:36
L11	14	("3385773" "4562301" "4906198" "5259110" "5290970" "5404637" "5479319" "5543586" "5548486" "5715595" "6018866" "6195883" "6272745").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/19 10:49
L19	52	("3601523" "4106187" "4283243" "4360570" "4622239" "4700474" "4777721" "4783247" "4884337" "4964948" "4995941" "5040717" "5053921" "5058265" "5133120" "5145691" "5220723" "5274916" "5451721" "5456004" "5471091" "5532516" "5540779" "5578151" "5591353" "5610103" "5637834" "5662987" "5699613" "5744285" "5753976" "5761803" "5766670" "5822856" "5824155" "5851344" "5894985" "5906042" "5925414" "5994779" "6000129" "6009620" "6015083" "6027006" "6079100" "6090474" "6106891" "6138350" "6153508" "6276055" "6281448" "6282782").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/19 11:11

4/19/06

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L20	168	("3335327" "3384879" "3615913" "3770529" "3808576" "3857683" "3923359" "4024629" "4090667" "4146863" "4238839" "4245273" "4247981" "4386051" "4399372" "4413272" "4420820" "4424578" "4433331" "4434134" "4455495" "4458297" "4488262" "4491860" "4507756" "4507757" "4547830" "4562639" "4565712" "4566186" "4569120" "4569121" "4585490" "4590589" "4609241" "4642160" "4651409" "4652974" "4678889" "4689411" "4700116" "4700214" "4710592" "4721868" "4726991" "4731704" "4732780" "4748490" "4757359" "4780670" "4786904" "4789760" "4791075" "4792646" "4792835" "4796074" "4796075" "4799128" "4799984" "4803595" "4808967" "4821142" "4823181" "4829404" "4839864" "4840924" "4841099" "4845315" "4847732" "4864165" "4873506" "4874711" "4876220" "4881114" "4882611" "4888574" "4888665" "4892776" "4893167" "4897836" "4899205" "4910418" "4914055" "4915983" "4916809" "4920454" "4924287" "4933738" "4935584" "4937475" "4943538" "4949084" "4964948" "4969124" "4974048" "4977357" "4992333" "5003486" "5014002" "5027191" "5030113" "5055321" "5055973" "5060116" "5068634" "5077451" "5087589" "5092032" "5097593" "5099149" "5099380" "5106773" "5120679" "5142263" "5144567" "5148265" "5148355" "5155577"	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/19 11:13
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EAST Search History

L21	65	(print\$3 wiring circuit) near3 (board substrate) with (hole via) and (attach\$3 mounting) with (board substrate) with (chip ic semiconductor (\$5electronic electrical) near2 (component device element)) same solder\$3 and (fill\$3 dispens\$3) with solder with (paste ink) with (hole via)	USPAT; EPO; JPO	OR	ON	2006/04/19 13:01
S60	424	"29"/\$.ccls. and (print\$3 wiring circuit) near3 (board substrate) with (hole via) and (attach\$3 mounting) with (board substrate) with (chip ic semiconductor (\$5electronic electrical) near2 (component device element)) same solder\$3	USPAT; EPO; JPO	OR	ON	2006/04/18 16:32
S61	12	"29"/\$.ccls. and (print\$3 wiring circuit) near3 (board substrate) with (hole via) and (attach\$3 mounting) with (board substrate) with (chip ic semiconductor (\$5electronic electrical) near2 (component device element)) same solder\$3 and juxtapos\$3	USPAT; EPO; JPO	OR	ON	2006/04/18 16:36
S62	75	"29"/\$.ccls. and (print\$3 wiring circuit) near3 (board substrate) with (hole via) and (attach\$3 mounting) with (board substrate) with (chip ic semiconductor (\$5electronic electrical) near2 (component device element)) same solder\$3 and (fill\$3 dispens\$3) with solder with (hole via)	USPAT; EPO; JPO	OR	ON	2006/04/18 17:48
S63	57	("4967314").URPN.	USPAT	OR	ON	2006/04/18 16:41
S64	74	"174"/\$.ccls. and (print\$3 wiring circuit) near3 (board substrate) with (hole via) and (attach\$3 mounting) with (board substrate) with (chip ic semiconductor (\$5electronic electrical) near2 (component device element)) same solder\$3 and (fill\$3 dispens\$3) with solder with (hole via) not S62	USPAT; EPO; JPO	OR	ON	2006/04/18 17:53
S65	14	"361"/\$.ccls. and (print\$3 wiring circuit) near3 (board substrate) with (hole via) and (attach\$3 mounting) with (board substrate) with (chip ic semiconductor (\$5electronic electrical) near2 (component device element)) same solder\$3 and (fill\$3 dispens\$3) with solder with (hole via) not S62 not S64	USPAT; EPO; JPO	OR	ON	2006/04/18 17:54

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S66	4	"428"/\$.ccls. and (print\$3 wiring circuit) near3 (board substrate) with (hole via) and (attach\$3 mounting) with (board substrate) with (chip ic semiconductor (\$5electronic electrical) near2 (component device element)) same solder\$3 and (fill\$3 dispens\$3) with solder with (hole via) not S62 not S64 not S65	USPAT; EPO; JPO	OR	ON	2006/04/19 13:00
S67	108	"257"/\$.ccls. and (print\$3 wiring circuit) near3 (board substrate) with (hole via) and (attach\$3 mounting) with (board substrate) with (chip ic semiconductor (\$5electronic electrical) near2 (component device element)) same solder\$3 and (fill\$3 dispens\$3) with solder with (hole via) not S62 not S64 not S65	USPAT; EPO; JPO	OR	ON	2006/04/18 17:55
S72	79	("5407864").URPN.	USPAT	OR	ON	2006/04/18 18:02